

# **Dual P-Channel 30-V (D-S) MOSFET**

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>d, e</sup>	Q <sub>g</sub> (Typ.)			
- 30	0.029 at V <sub>GS</sub> = - 10 V	- 7.3	17 nC			
- 30	0.039 at V <sub>GS</sub> = - 4.5 V	- 6.3	17 110			

#### **FEATURES**

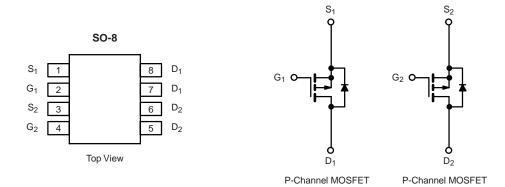
- Halogen-free
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % UIS Tested



RoHS

#### **APPLICATIONS**

· Load Switches



<b>ABSOLUTE MAXIMUM RATINGS</b>	A = 25 °C, unless other	erwise noted		
Parameter	Symbol Limit		Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		- 7.3 <sup>e</sup>	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 70 °C	1 . [	- 7.0 <sup>e</sup>	
Continuous Diam Current (1) = 130 C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 7.3 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 5.9 <sup>a, b</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	- 32 <sup>e</sup>		
Continuous Course Drain Diade Current	T <sub>C</sub> = 25 °C	I.	- 4.1	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 2.0 <sup>a, b</sup>	
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mm	E <sub>AS</sub>	20	mJ
	T <sub>C</sub> = 25 °C		5.0	
Maximum Davin Disaination	T <sub>C</sub> = 70 °C	В	3.2	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5 <sup>a, b</sup>	VV
	T <sub>A</sub> = 70 °C		1.6 <sup>a, b</sup>	
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	$R_{thJF}$	20	25	C/VV	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on  $T_C = 25$  °C.
- e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L = 250 uA		- 31		m\//9C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	ID = - 250 HA		4.5		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Proin Current	,	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 5	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
Davis Ossans Os Otata Basista and	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 6.3 A	0.035				
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 6.2 A		0.040		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 6.1 A		23		S	
Dynamic <sup>b</sup>					•		
Input Capacitance	C <sub>iss</sub>			1350		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		215			
Reverse Transfer Capacitance	C <sub>rss</sub>			185			
Total Cata Chausa		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6.1 \text{ A}$		32	50	nC	
Total Gate Charge				15	25		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6.1 \text{ A}$		4			
Gate-Drain Charge	$Q_{gd}$			7.5			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		5.8		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$		8	15		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		45	70		
Fall Time	t <sub>f</sub>			12	25		
Turn-On Delay Time	t <sub>d(on)</sub>			42	70	ns	
Rise Time	ì, í	$V_{DD}$ = - 15 V, $R_L$ = 15 $\Omega$		35	60	<u></u>	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		40	70		
Fall Time	t <sub>f</sub>	]		16	30		
<b>Drain-Source Body Diode Characterist</b>	ics						
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 4.1	Λ	
Pulse Diode Forward Current	I <sub>SM</sub>	-			- 32	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = -2 A, V <sub>GS</sub> = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			34	60	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 2 A d1/d+ 400 A/:- T 05 00		22	40	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °C$	25 -0	11			
Reverse Recovery Rise Time	t <sub>b</sub>			23		ns	

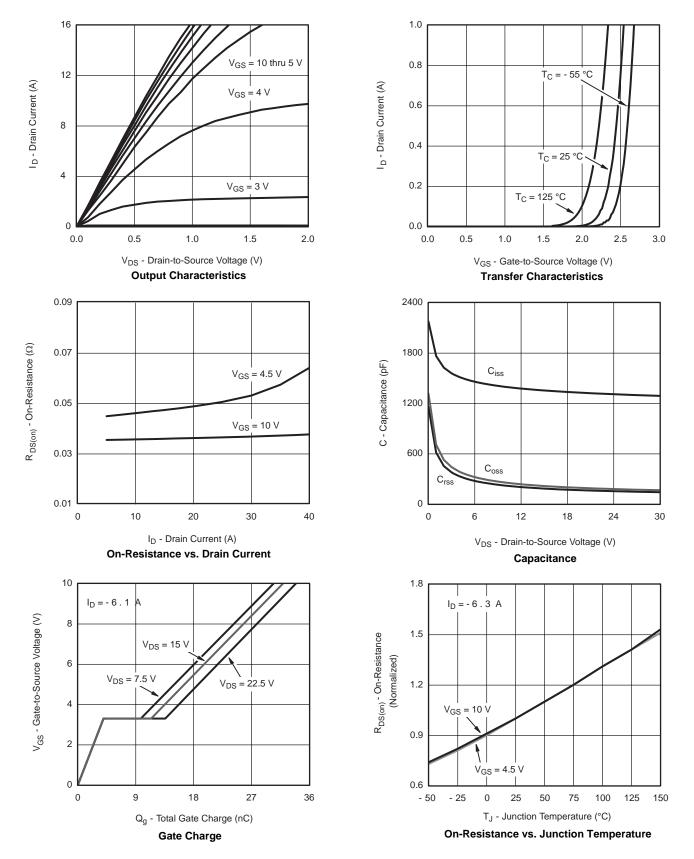
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

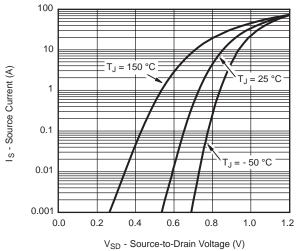


#### TYPICAL CHARACTERISTICS 25 C, unless otherwise noted

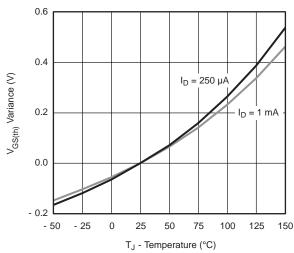




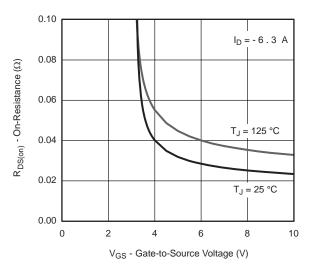
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



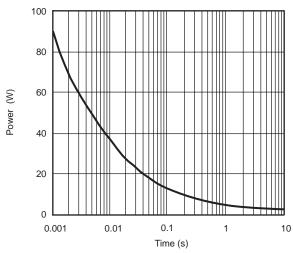
#### Source-Drain Diode Forward Voltage



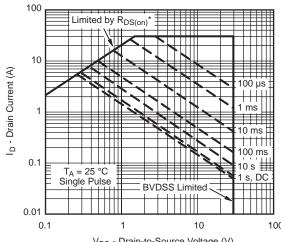
#### **Threshold Voltage**



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



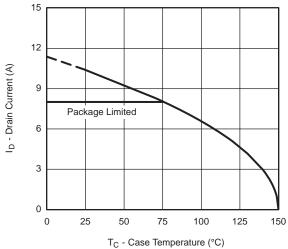
V<sub>DS</sub> - Drain-to-Source Voltage (V)

Safe Operating Area

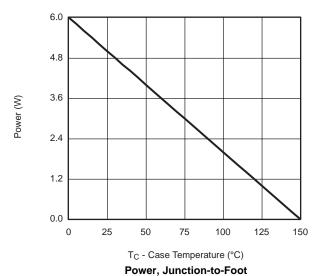
<sup>\*</sup>  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



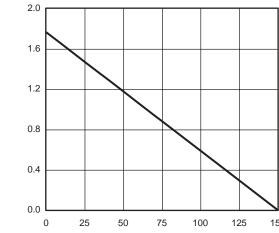
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



#### **Current Derating\***







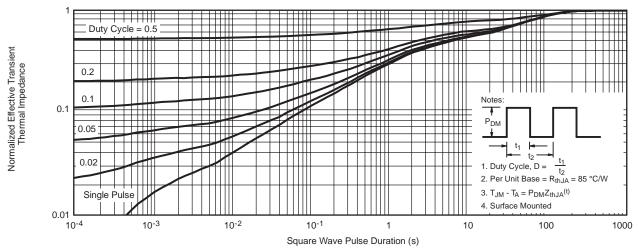
T<sub>A</sub> - Ambient Temperature (°C)

Power Derating, Junction-to-Ambient

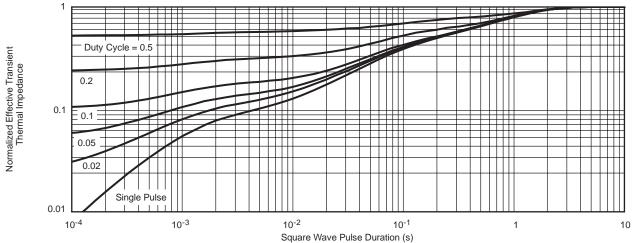
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



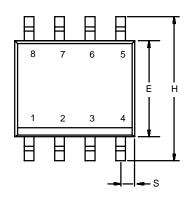
Normalized Thermal Transient Impedance, Junction-to-Foot

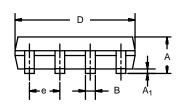
E-mail: China@VBsemi TEL:86-755-83251052

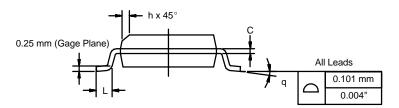
6



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







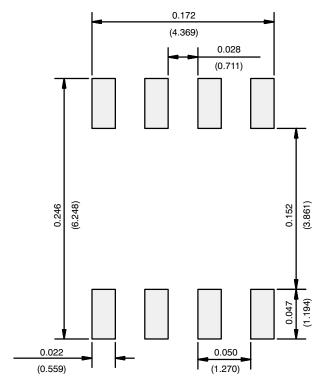
	MILLIM	IETERS	INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Rev I 11-Sen-06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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